

SPECIFICATION

1.General Characteristics

3.0mm Micro-Fit Wafer 1XXX SMT 90°
With DIP Boardlock Black Insulator
Tin Plated Tape & Reel 250 PCS/Reel

2.Material&Finish

Insulator:LCP(UL94V-0),Black
Contact:Brass,Tin Plated
Solder Tabs:Brass,Tin Plated

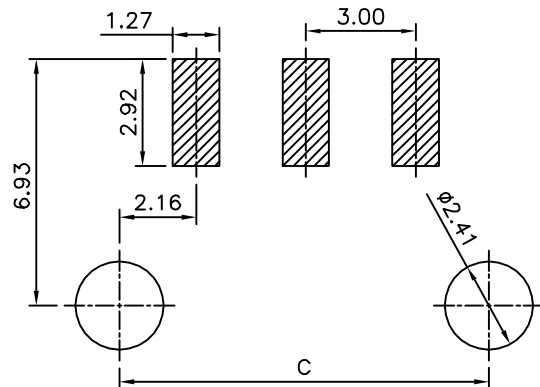
3.Electrical Characteristics

Current Rating:5A AC,DC
Voltage Rating:250V AC,DC
Withstanding Voltage:1500V AC/Minute
Insulation Resistance:1000 Megaohms Min.
Contact Resistance:20 Milliohms Max.

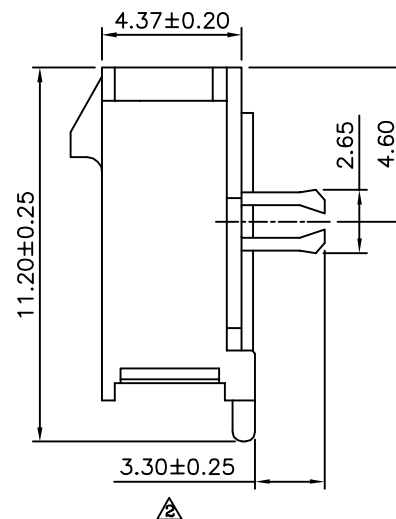
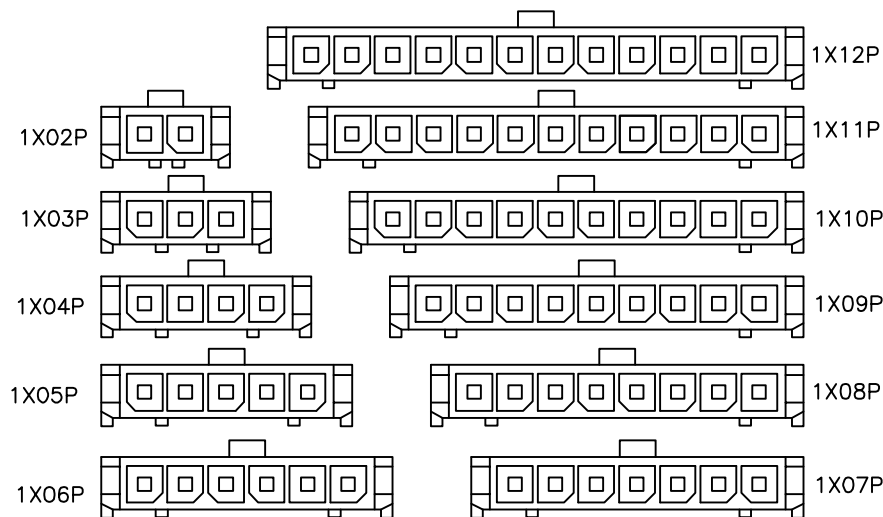
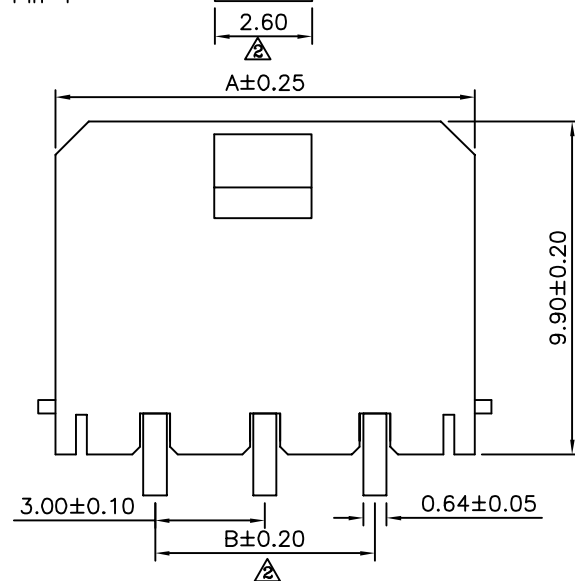
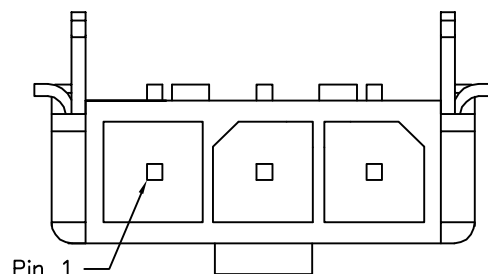
4.Environmental Characteristics

Temperature Range:-25°C~+85°C

5.RoHS Compliant



Recommended P.C.B. Layout



Pin	A	B	C
02	9.65	3.00	7.30
03	12.65	6.00	10.30
04	15.65	9.00	13.30
05	18.65	12.00	16.30
06	21.65	15.00	19.30
07	24.65	18.00	22.30
08	27.65	21.00	25.30
09	30.65	24.00	28.30
10	33.65	27.00	31.30
11	36.65	30.00	34.30
12	39.65	33.00	37.30

4UCON 元化興業股份有限公司
4UCON TECHNOLOGY INC.

DRAWING No.

21134

APPROVED BY

MEI

CHECKED BY

HZF

DRAWING BY

CYP

UNLESS OTHERWISE
SPECIFIED
TOLERANCES ARE

X₁ ±0.30
X₂ ±0.25
X₃ ±0.20
XXX ±0.20
ANG. ±1°

SCALE

NONE

REV.

A2

UNIT

mm



NO.	REV.	REVISIONS	CHK	DATE
A2		Modify Data	HZF	03/23/2016
A1		Modify P/N:MIF1XXXPWZ-H --> MIF1XXXPWZ-R2H5-H	HZF	12/08/2014
A0		NEW RELEASE	HZF	08/02/2012